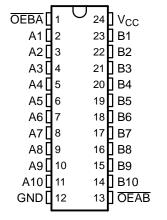


FEATURES

- Operates From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 6.4 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2 V at V_{CC} = 3.3 V, T_A = 25°C
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DB, DGV, DW, NS, OR PW PACKAGE (TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

This 10-bit bus transceiver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74LVC861A is designed for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing.

This device allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable (OEAB and OEBA) inputs.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

T _A	PAC	KAGE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SOIC DW	Tube of 25	SN74LVC861ADW	1.1/0.004.4
	SOIC – DW	Reel of 2000	SN74LVC861ADWR	LVC861A
4000 4 0500	SOP - NS	Reel of 2000	SN74LVC861ANSR	LVC861A
	SSOP - DB	Reel of 2000	SN74LVC861ADBR	LC861A
–40°C to 85°C		Tube of 60	SN74LVC861APW	
	TSSOP - PW	Reel of 2000	SN74LVC861APWR	LC861A
		Reel of 250	SN74LVC861APWT	
	TVSOP - DGV	Reel of 2000	SN74LVC861ADGVR	LC861A

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



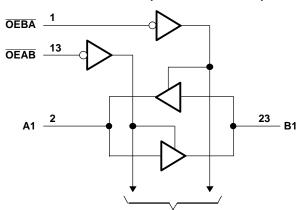
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FUNCTION TABLE

INP	UTS	OPERATION
OEAB	OEBA	OPERATION
L	Н	A data to B bus
Н	L	B data to A bus
Н	Н	Isolation
L	L	Latch A and B (A = B)

LOGIC DIAGRAM (POSITIVE LOGIC)



To Nine Other Channels



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT	
V_{CC}	Supply voltage range	-0.5	6.5	V		
V_{I}	Input voltage range ⁽²⁾		-0.5	6.5	V	
Vo	Voltage range applied to any output in the high-in	npedance or power-off state (2)(3)	-0.5	6.5	V	
Vo	Voltage range applied to any output in the high or	-0.5	V _{CC} + 0.5	V		
I _{IK}	Input clamp current	V _I < 0		-50	mA	
I _{OK}	Output clamp current	V _O < 0		-50	mA	
Io	Continuous output current		±50	mA		
	Continuous current through V _{CC} or GND			±100	mA	
		DB package		63		
		DGV package		86		
θ_{JA}	Package thermal impedance (4)	DW package		46	°C/W	
		NS package		65		
		PW package		88		
T _{stg}	Storage temperature range		-65	150	°C	

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT	
V	Cumply voltage	Operating	1.65	3.6	V	
V_{CC}	Supply voltage	Data retention only	1.5		V	
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}			
V_{IH}	High-level input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V	
		V _{CC} = 2.7 V to 3.6 V	2			
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		V _{CC} = 2.7 V to 3.6 V		0.8		
VI	Input voltage		0	5.5	V	
., .	Outrot valta ea	High or low state	0	V_{CC}	V	
V _O	Output voltage	3-state	0	5.5	V	
		V _{CC} = 1.65 V		-4		
	High lavel autout avenue	V _{CC} = 2.3 V		-8	mA	
I _{OH}	High-level output current	V _{CC} = 2.7 V		-12		
		V _{CC} = 3 V		-24		
		V _{CC} = 1.65 V		4		
	Laveland autout aumant	V _{CC} = 2.3 V		8	A	
I _{OL}	Low-level output current	V _{CC} = 2.7 V		12	mA	
		V _{CC} = 3 V		24		
Δt/Δν	Input transition rise or fall rate			10	ns/V	
T _A	Operating free-air temperature		-40	85	°C	

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

⁽²⁾ The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

³⁾ The value of V_{CC} is provided in the recommended operating conditions table.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51-7.



Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

P/	PARAMETER TEST CONDITIONS		V _{cc}	MIN	TYP ⁽¹⁾	MAX	UNIT	
		$I_{OH} = -100 \mu A$	1.65 V to 3.6 V	V _{CC} - 0.2				
		$I_{OH} = -4 \text{ mA}$		1.65 V	1.2			V
\/		$I_{OH} = -8 \text{ mA}$		2.3 V	1.7			
V _{OH}		12 m		2.7 V	2.2			V
		$I_{OH} = -12 \text{ mA}$		3 V	2.4			
		I _{OH} = -24 mA	3 V	2.2				
		I _{OL} = 100 μA		1.65 V to 3.6 V			0.2	
		I _{OL} = 4 mA	1.65 V			0.45	V	
V_{OL}		I _{OL} = 8 mA	2.3 V			0.7		
		I _{OL} = 12 mA	2.7 V			0.4		
		I _{OL} = 24 mA	3 V			0.55		
I	Control inputs	V _I = 0 to 5.5 V		3.6 V			±5	μΑ
I _{off}		V_I or $V_O = 5.5 \text{ V}$		0			±10	μΑ
I _{OZ} ⁽²⁾		V _O = 0 to 5.5 V		3.6 V			±10	μΑ
Icc		V _I = V _{CC} or GND	1 - 0	201/			10	
		$\frac{1}{3.6 \text{ V} \le \text{V}_1 \le 5.5 \text{ V}^{(3)}} \text{I}_0 = 0$		3.6 V			10	μΑ
ΔI_{CC}		One input at V _{CC} - 0.6 V, Other in	outs at V _{CC} or GND	2.7 V to 3.6 V			500	μΑ
C _i	Control inputs	V _I = V _{CC} or GND		3.3 V		5		pF
C _{io}	A or B ports	$V_O = V_{CC}$ or GND		3.3 V		7		pF

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1		V _{CC} = 2 ± 0.2		V _{CC} =	2.7 V	V _{CC} = 3 ± 0.3	3.3 V 3 V	UNIT
	(INPOT)	(001F01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A or B	B or A	(1)	(1)	(1)	(1)		6.8	1.3	6.4	ns
t _{en}	OEAB or OEBA	A or B	(1)	(1)	(1)	(1)		8.2	1	7	ns
t _{dis}	OEAB or OEBA	A or B	(1)	(1)	(1)	(1)		6.6	1.7	5.9	ns
t _{sk(o)}										1	ns

⁽¹⁾ This information was not available at the time of publication.

Operating Characteristics

 $T_A = 25^{\circ}C$

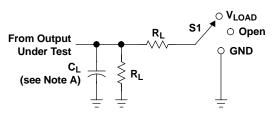
	PARAMETER	TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT	
=	Power dissipation capacitance Outputs ena		f 10 MH=	(1)	(1)	29	"F
	C _{pd} per transceiver O	Outputs disabled	f = 10 MHz	(1)	(1)	5	pF

(1) This information was not available at the time of publication.

⁽¹⁾ All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$. (2) For I/O ports, the parameter I_{OZ} includes the input leakage current. (3) This applies in the disabled state only.



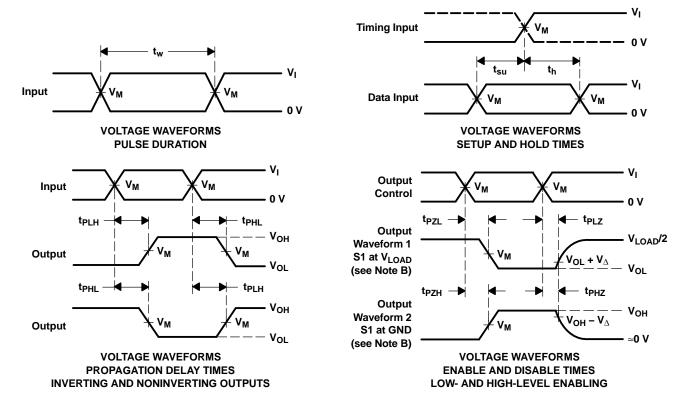
PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

LOAD CIRCUIT

.,	INPUTS		.,	.,		_	.,
V _{CC}	VI	t _r /t _f	V _M	V _{LOAD}	CL	R _L	$oldsymbol{V}_{\Delta}$
1.8 V \pm 0.15 V	v _{cc}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVC861ADBLE	OBSOLETE	SSOP	DB	24		TBD	Call TI	Call TI
SN74LVC861ADBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC861ADBRE4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC861ADGVR	ACTIVE	TVSOP	DGV	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC861ADGVRE4	ACTIVE	TVSOP	DGV	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC861ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC861ADWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC861ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC861ADWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC861ANSR	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC861ANSRE4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC861APW	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC861APWE4	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC861APWLE	OBSOLETE	TSSOP	PW	24		TBD	Call TI	Call TI
SN74LVC861APWR	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC861APWRE4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC861APWT	ACTIVE	TSSOP	PW	24	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC861APWTE4	ACTIVE	TSSOP	PW	24	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

6-Dec-2006

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

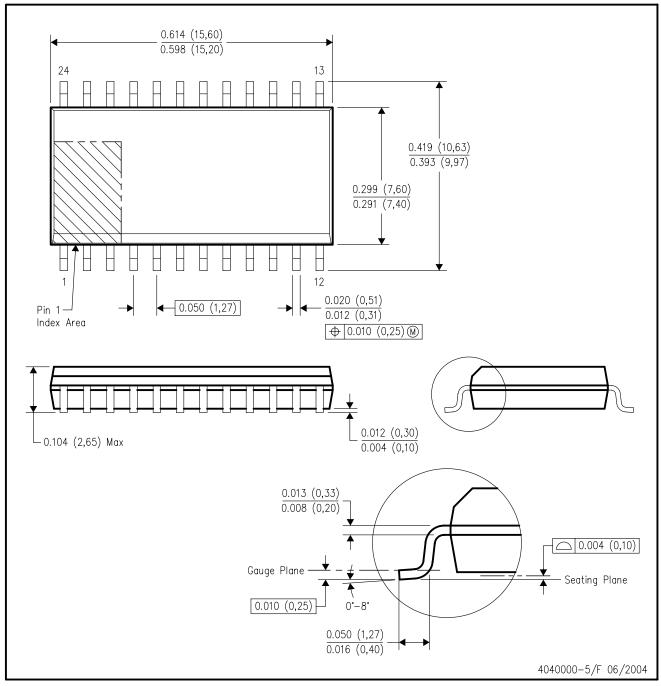
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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